

What is claimed is:

1. An electron tube having a ring-less getter of a tablet shape in a vessel,
5 wherein a light is irradiated on the ring-less getter to thereby activate the ring-less getter.
- 10 2. The electron tube of claim 1, wherein the ring-less getter is an evaporation type ring-less getter; and an evaporated getter generated by irradiating the light on the ring-less getter forms a getter film in the vessel of the electron tube.
- 15 3. The electron tube of claim 1, wherein the ring-less getter is a non-evaporation type ring-less getter; and the light is irradiated on the ring-less getter to selectively heat the ring-less getter, thereby activating the ring-less getter.
- 20 4. The electron tube of claim 1, wherein the ring-less getter is installed on the vessel including at least one substrate of the electron tube.
- 25 5. The electron tube of claim 1, wherein the ring-less getter is installed on a component of the electron tube.

6. The electron tube of claim 1, wherein the ring-less getter is mounted on a metallic layer formed in the vessel and a metallic wire is hanged to the ring-less getter and then two end portions of the metallic wire are welded to the
5 metallic layer.

7. The electron tube of claim 1, wherein two end portions of a metallic wire installed on the ring-less getter are welded to a metallic layer side formed in the vessel.

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8. The electron tube of claim 7, wherein the metallic wire is mounted on the metallic layer on the ring-less getter.

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9. The electron tube of claim 8, wherein the metallic wire is mounted on the metallic layer parallel to a display region of the electron tube.

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10. The electron tube of claim 6 or 7, wherein the vessel is a vacuum vessel; the welding is performed by employing an ultrasonic bonding; the metallic wire is a bonding wire; and the metallic layer is a metallic thin film.

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11. The electron tube of claim 1, wherein the ring-less getter includes a getter material layer and a metallic layer; and the metallic layer of the ring-less getter is welded to a corresponding metallic layer formed in the

vessel.

12. The electron tube of claim 1, wherein the ring-less getter includes a getter material layer and a metallic layer formed by press forming getter material powder and metal powder, respectively; and the metallic layer of the ring-less getter is welded to a metallic layer formed in the vessel.
- 10 13. The electron tube of claim 1, wherein the ring-less getter includes a getter material layer and a metallic layer formed by press forming the getter material powder and a metal film/plate, respectively; and the metallic layer of the ring-less getter is welded to a metallic layer formed in the vessel.
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14. The electron tube of claim 1, wherein the ring-less getter includes a getter material layer and a metallic wire formed by pressing getter material powder and a metal wire, respectively; and the metallic wire of the ring-less getter is welded to a metallic layer formed in the vessel.
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15. The electron tube of claim 1, wherein the ring-less getter includes a metallic layer and a getter material layer having a getter material film; and the metallic wire of the ring-less getter is welded to a metallic layer formed in the
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vessel.

16. The electron tube of one of claims 11 to 15, wherein
the getter material layer of the ring-less getter is
5 evaporated by the light and there is formed a getter mirror
film on an inner side of a corresponding substrate or a
corresponding component of the electron tube facing to the
substrate or the component where the ring-less getter is
fixed.

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17. The electron tube of one of claims 11 to 15, wherein
the light is irradiated on the getter material layer of the
ring-less getter from outside of a corresponding substrate
facing to the substrate or the component where the ring-less
15 getter is fixed; and there is formed a getter mirror film on
an inner side of the corresponding substrate.

18. The electron tube of one of claims 11 to 15, wherein
the vessel is a vacuum vessel; the welding is performed by
20 employing an ultrasonic bonding; and the metallic wire is a
bonding wire; and the metallic layer is a metallic thin film.

19. The electron tube of one of claims 1, 6, 7 and 11 to 15,
wherein the electron tube is a fluorescent display device.

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20. A method for manufacturing an electron tube including a front substrate and a back substrate,

wherein a wiring and an electrode are formed on the front substrate and/or the back substrate; a component is mounted on the front substrate and/or the back substrate; a ring-less getter is mounted on at least one of the front substrate, the back substrate and the component; a vessel is assembled and sealed so that the front substrate faces the back substrate; a light is irradiated on the ring-less getter from outside of the sealed vessel, thereby activating the ring-less getter.

21. A method for manufacturing an electron tube including a front substrate and a back substrate,

wherein a wiring and an electrode are formed on the front substrate and/or the back substrate; a component having a ring-less getter of a tablet shape installed thereon is mounted on the front substrate and/or the back substrate; a vessel is assembled and sealed so that the front substrate faces the back substrate; a light is irradiated on the ring-less getter from outside of the sealed vessel, thereby activating the ring-less getter.

22. The method of claim 20 or 21, wherein the ring-less getter is an evaporation type ring-less getter; and evaporated getter generated by irradiating the light on the

ring-less getter forms a getter film in the vessel of the electron tube.

23. The method of claim 20 or 21, wherein the light is a
5 laser beam.

24. The method of claim 20 or 21, wherein the ring-less getter is installed by employing either an ultrasonic bonding technique or an ultrasonic bonding technique.

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